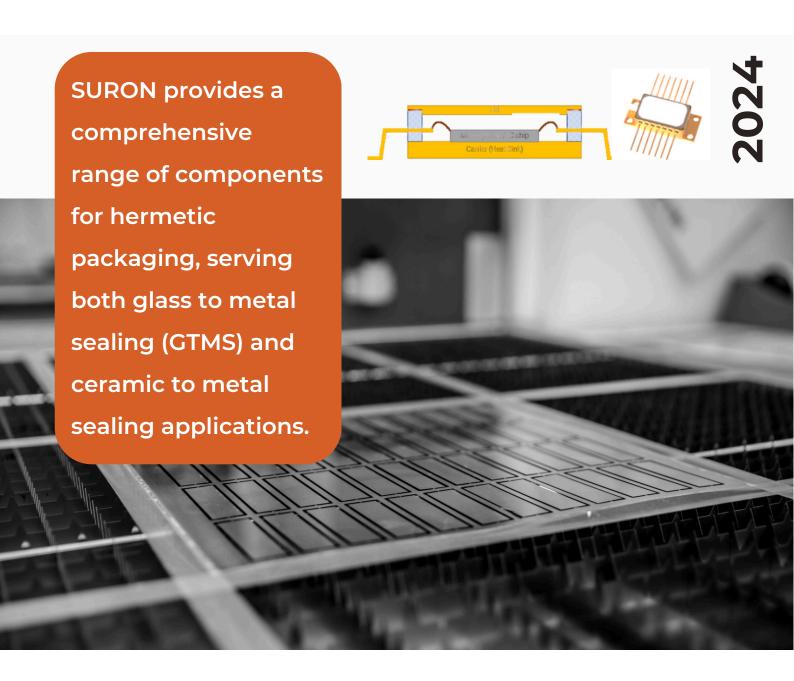
HERMETIC PACKAGING

Components



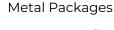


HERMETIC PACKAGING

Components



SURON provides a comprehensive range of components for microelectronic hermetic packaging. With cutting-edge technological expertise, our in-house capabilities include plating and coating.





Carriers/Heat **Spreaders**



Lids





- Lids
- **Metal Packages**
- **Heat Dissipation** Substrates
- Rings



- Gold Plating **Immersion & Electrolytic** (Hard and Soft)
- Nickel Plating **Electroless & Electrolytic**







- **Materials**
 - CTE Compatible to Glass: Kovar, Alloy42 and more
 - Thermal Management Alloys: MoCu, WCu and more

